

1. Part No. Expression:

**W Q 3 2 2 5 - 1 0 2 J**

(a) (b) (c) (d)

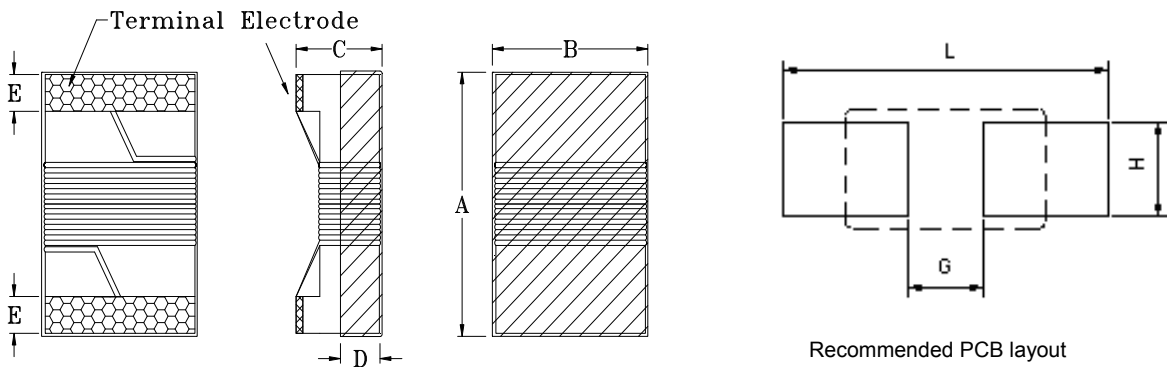
(a) Series Code

(c) Inductance Code

(b) Dimension Code

(d) Tolerance Code

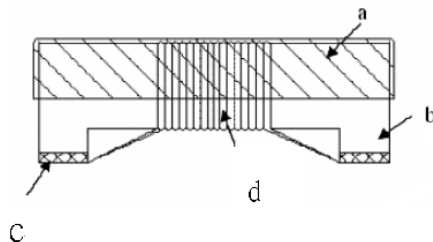
2. Configuration & Dimensions:



Unit: mm

A	B	C	D	E	L	G	H
3.60 Max.	2.80 Max.	2.60 Max.	0.80 Ref.	0.55 ± 0.1	3.82 Ref.	1.78 Ref.	2.80 Ref.

3. Material List:



(a) Upper Plate

(b) Core

(c) Termination

(d) Wire

NOTE: Specifications subject to change without notice. Please check our website for latest information.



**4. General Specification:**

- (a) Reliability test for this part meets AEC-Q200 standard
- (b) Operating Temp. : -55°C to +125°C(Including self - temperature rise)
- (c) Storage Temp. : -55°C to +125°C (on board)
- (d) Humidity Range: 85 ± 3% RH
- (e) Storage Condition (Component in its packaging)
  - i) Temperature: Less than 40°C
  - ii) Humidity : 60% RH

**5. Electrical Characteristics:**

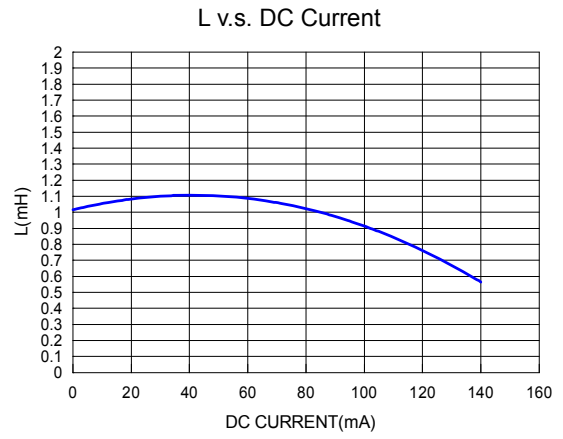
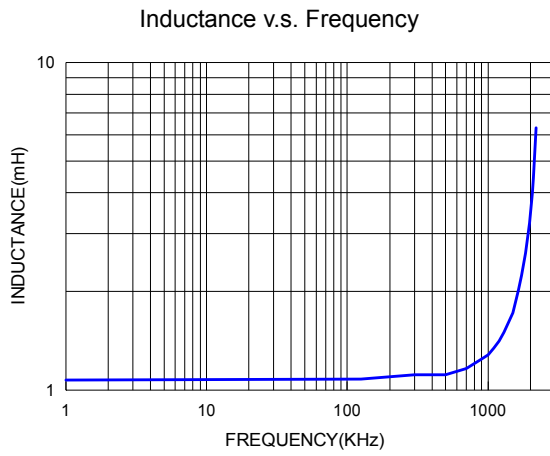
Part Number	Inductance (uH)	Test Frequency (Hz)	Q Min.	Rated Current (mA) Max.	DCR (Ω) Max.	SRF (MHz) Min.
WQ3225-102J	1080±5%	0.1V/125K	15	50	35	1.5
WQ3225-132J	1340±5%	0.1V/125K	15	50	42	1.5

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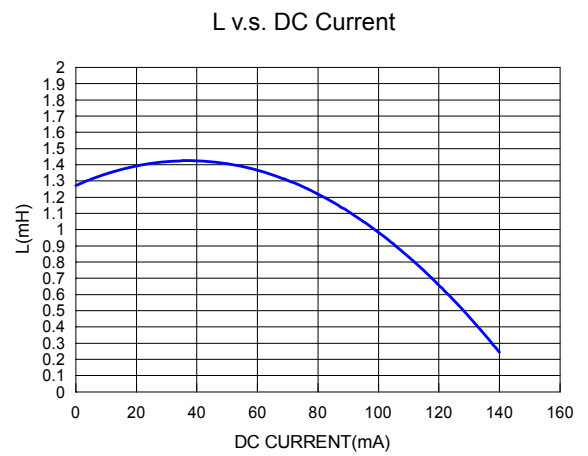
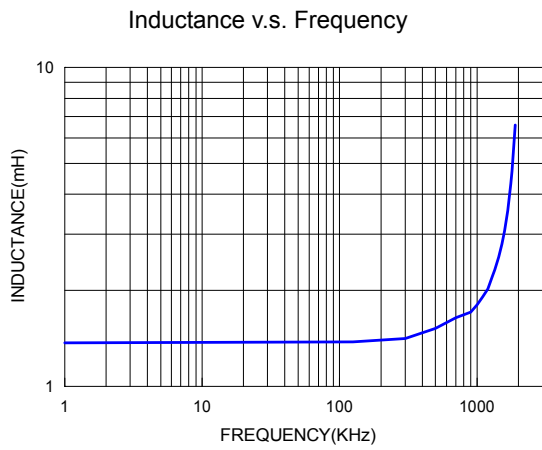


6. Characteristics Curves:

WQ3225-102J



WQ3225-132J



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## 7. Soldering:

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

### 7-1 Solder Re-flow

Recommended temperature profiles for re-flow soldering in Figure 1.

### 7-2 Soldering Iron (Figure 2)

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note :

- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (Max.)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (Max.)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 sec.

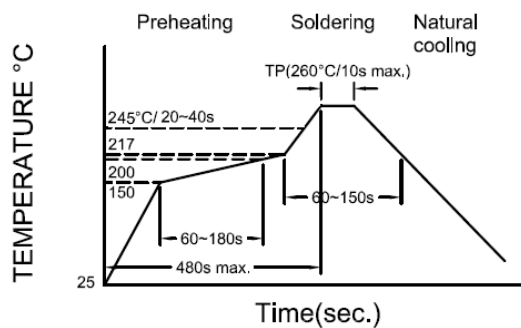


Figure 1. : Re-flow Soldering time  
3 times max

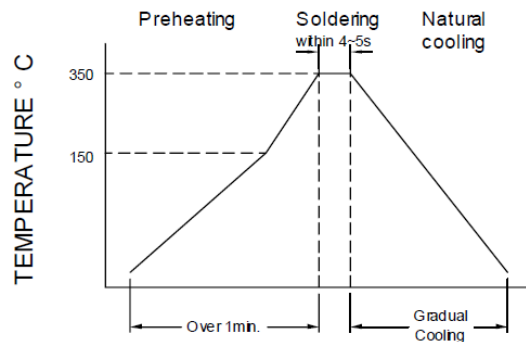
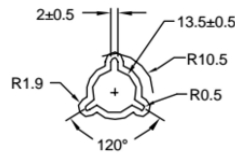
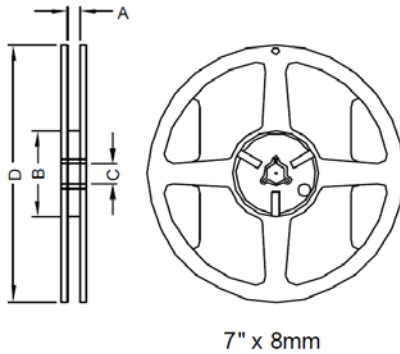


Figure 2. : Iron Soldering time  
1 times max

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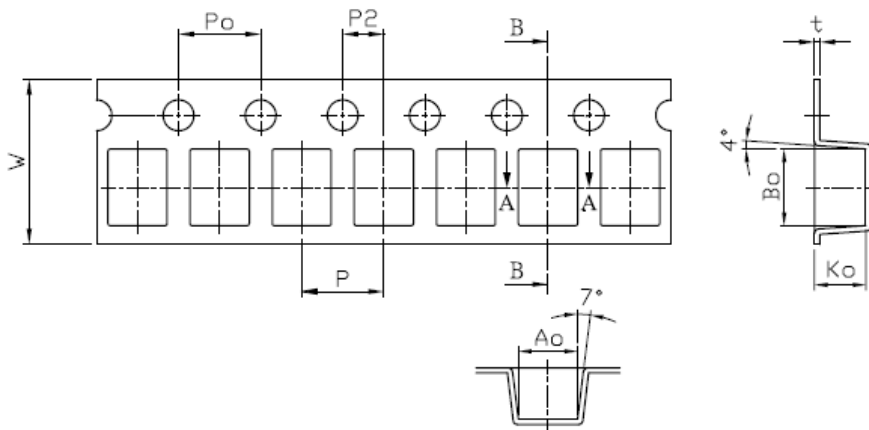
8. Packaging Information:

8-1 Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	9.0±0.5	60.0±2.0	13.5±0.5	178±2.0

8-2 Tape Dimension



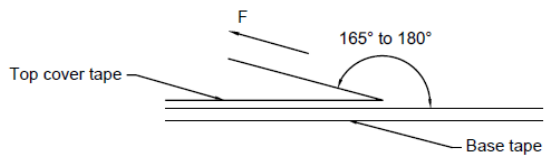
Size	P(mm)	Po(mm)	P2(mm)	Bo(mm)	Ao(mm)	Ko(mm)	W(mm)	t(mm)
WQ3225	4.00±0.10	4.00±0.10	2.00±0.05	3.72±0.10	2.88±0.10	2.50±0.10	8.00±0.10	0.26±0.05

8-3 Packaging Quantity

Chip Size	WQ3225
Chip/Reel	2,000

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8-4 Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

**Application Notice:**

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.

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